

XP-002159458

AN - 1979-86850B [48]

A - [001] 011 03& 05- 062 064 148 151 229 230 308 311 329 331 38- 475 541  
546 623 627 723

CPY - HODO

DC - A25 A26

FS - CPI

IC - C08L81/04 ; C08L83/04

KS - 0011 0016 0210 0222 0228 1280 1303 1306 2211 2267 2511 2600 2737

MC - A05-J05 A06-A00E A08-A04A

PA - (HODO ) HODOGAYA CHEM IND CO LTD

PN - JP54135845 A 19791022 DW197948 000pp

- JP60010548B B 19850318 DW198515 000pp

PR - JP19780043199 19780414

XIC - C08L-081/04 ; C08L-083/04

AB - J54135845 Resinous compsn. comprises polyphenylene sulphide and silicone oil. By incorporating silicone oil, polyphenylene sulphide resin becomes sufficiently heat-resistant to prevent solder adhesion to it when electronics parts, etc. with the resin are assembled by soldering.

- Suitable silicone oils are polyorganosiloxanes or polydimethyl siloxane and polysiloxane modified with fluorine gp. or olefin gp. Compsn. suitably comprises  $\geq 25$  wt.% phenylene sulphide, 1-10 wt.% silicone oil, and the remainder reinforcing material, filler, etc.

IW - POLYPHENYLENE SULPHIDE RESIN IMPROVE HEAT RESISTANCE CONTAIN SILICONE OIL MODIFIED POLYSILOXANE CAN PREVENT SOLDER ADHESIVE  
IKW - POLYPHENYLENE SULPHIDE RESIN IMPROVE HEAT RESISTANCE CONTAIN SILICONE OIL MODIFIED POLYSILOXANE CAN PREVENT SOLDER ADHESIVE

NC - 001

OPD - 1978-04-14

ORD - 1979-10-22

PAW - (HODO ) HODOGAYA CHEM IND CO LTD

TI - Polyphenylene sulphide resin with improved heat resistance - contg. a silicone oil e.g. a modified polysiloxane, which can prevent solder adhesion